Technical Data Sheet

Silicone-base adhesive tapes T4082S

Features

- Stable bonding performance under a wide range of temperature environments, from low to high temperatures.
- Easy removal without adhesive residue and discoloration.

Structure		
Adhesive	Main component	Silicone
	Carrier	38µmPET
	Color	Blue
	Adhesive thickness (µm)	About 70
	Release paper thickness (µm)	_
	Bonding strength (N/20mm) *	6
	St'd size (width × length)	18mm × 50m
	* 180° peeling strength	

Suitable use

- Ideal for bonding difficult-to-bond materials such as silicone rubber, silicone form for electricity and electric devices.
- Ideal for temporary fixing of covers for audiovisual products and computers.
- Ideal for protection of products during transportation.
- Ideal for splicing of silicone release papers, plastic films and metallic foils.

Technical data

1. Bonding strength on various type of substrate (180° peeling)

<Test piece condition> Substrate: Stainless steel plate (SUS304) Tape width: 20mm Bonding condition: One stroke with 2-kg roller Measuring condition: 23°C±5°C 60%±20% RH Peeling speed: 300mm/min [Left at RT for one hour before measurement]



<results></results>		(N/20mn
	Initial	6
180° peeling strength	60°C 95%RH, after 8 hours	6
	40°C, after 8 hours	6











2. Holding power at different temperatures

<Test piece condition> Substrate: Stainless steel plate (SUS304) Bonding area: 25mm × 25mm Bonding condition: One stroke with 2-kg roller [Left at RT for one hour and measure creep length after one hour application of 1-kg load at each temperature]

<Results>

Measurement temperature (°C)	40	100
Creep length (mm)	0	0

Substrate

<Holding power test>



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